



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

Revisio

Datum:

Seite:

PRINTED CIRCUIT BOARDS

01

04.02.2013

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 200 FR4 35 L71.70 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_200_FR4_35_L71.70_p18

Layers	in μ	Material	Build-Up	Assembly				
Layer-1	35 μ	Copper	 (180 μ PrePreg-Type: 7628)					
	180 μ	Prepreg						
	180 μ	Prepreg						
	180 μ	Prepreg						
Layer-2	70 μ	Copper	 (180 μ PrePreg-Type: 7628)					
	710 μ	L-FR4						
Layer-3	70 μ	Copper				 (180 μ PrePreg-Type: 7628)		
	180 μ	Prepreg						
	180 μ	Prepreg						
	180 μ	Prepreg						
Layer-99	35 μ	Copper		 (180 μ PrePreg-Type: 7628)				

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